



PRODUCT SPECIFICATION

1 SCOPE

This product specification covers the Molex P/N:

Part Number	Applications	Part Description	Remarks
2003161001	Restricted (F-Cooling Fan)	MPDB_MOD_ASSY 8CKT KEY-B	
2003161101	General Market		
2003161002	Restricted (F-AWD)	MPDB_MOD_ASSY 8CKT KEY-A	
2003161102	General Market		
2003161003	Restricted (F-UREA)	MPDB_MOD_ASSY 8CKT KEY-C	
2003161103	General Market		
2003161021	Restricted (J-Glow Plug 12V)	MPDB_ASSY 8CKT KEY-A	
2003161121	General Market		
2003161022	Restricted (J-Glow Plug 24V)	MPDB_ASSY 8CKT KEY-B	
2003161122	General Market		

Product Introduction:

The μ PDB (Micro Power Distribution Box) product family has been developed to provide affordable flexibility and feature expansion to system level electrical distribution designs.

The product family is built on a single housing/header design that can accommodate three different connector cavitation options along with a standard printed circuit board size. This results in hundreds of possible configurations of fused or unfused power switching options.

A number of common configurations have already been developed and built for testing (these are detailed later in this document) and new standard configurations are planned. Additionally, requests for application specific configurations are welcome!

The three sealed connector options are from the Molex MX-150 family - ensuring outstanding durability and reliability. This, coupled with the extremely small package size (33mm x 47mm x 78mm w/o connector) delivers a sealed miniature power distribution module that can be packaged virtually anywhere on the vehicle using the standard clip slots on the module housing.

PENDING
APPROVAL

REVISION: B	ECR/ECN INFORMATION: ER No: 626413 DATE: 2019 / 10 / 28	TITLE: PS: MICRO-PDB_MODULE ASSEMBLY	SHEET No. 1 of 12
DOCUMENT NUMBER: PS-200316-1000	CREATED / REVISED BY: E.H. CHEONG	CHECKED BY: E.H. CHEONG	APPROVED BY: RON BAUMAN

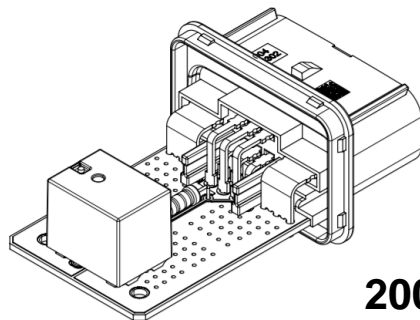
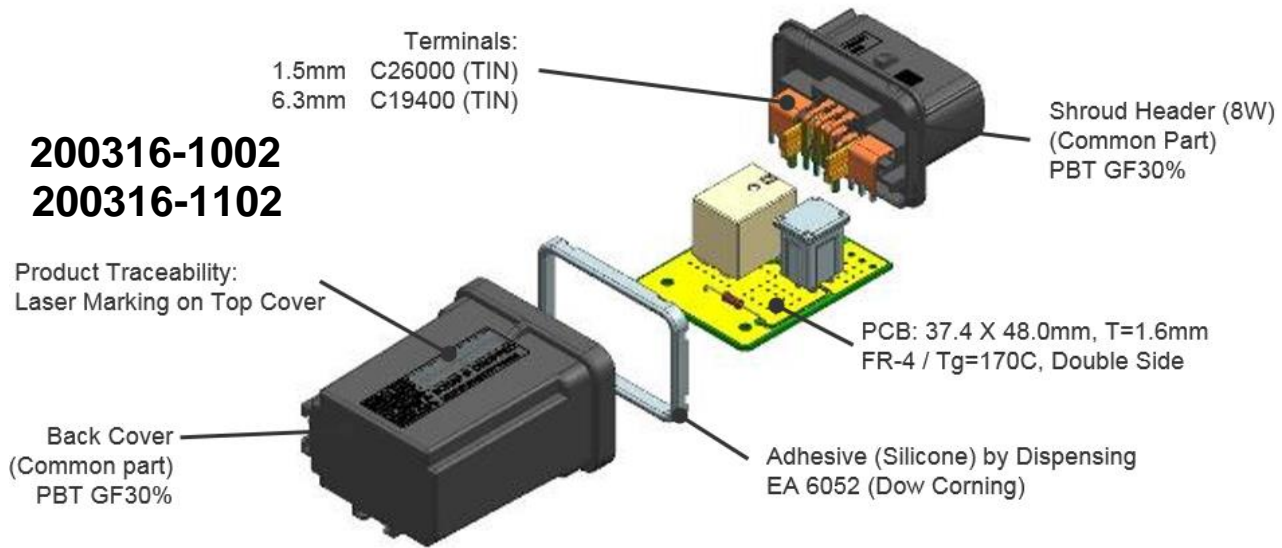


PRODUCT SPECIFICATION

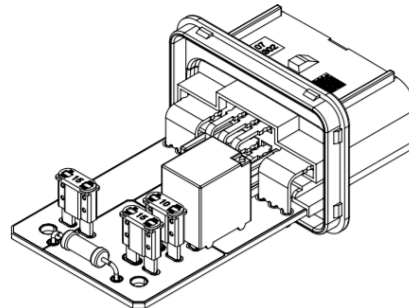
2. PRODUCT DESCRIPTION

2.1 PRODUCT NAME: MICRO-PDB (POWER DISTRIBUTION BOX)

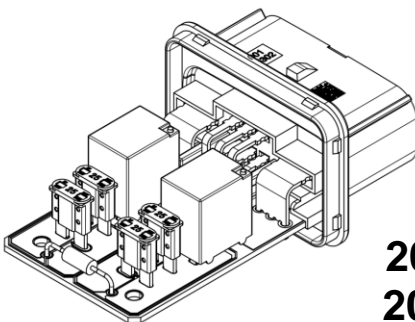
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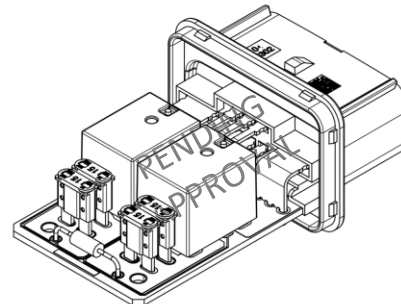
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200316-1003
200316-1103



200316-1021
200316-1121



200316-1022
200316-1122

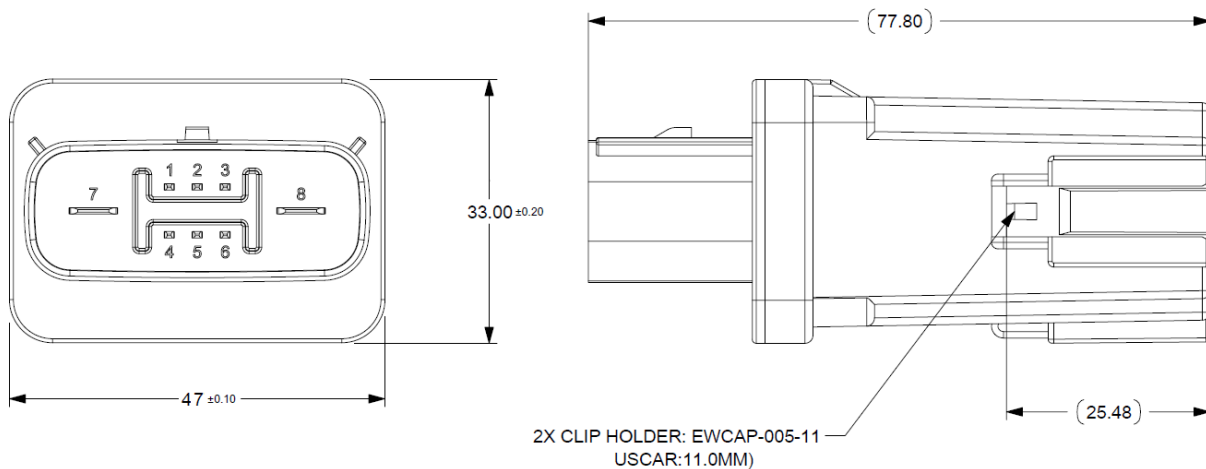
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DOCUMENT NUMBER: PS-200316-1000	CREATED / REVISED BY: E.H. CHEONG	CHECKED BY: E.H. CHEONG	APPROVED BY: RON BAUMAN



PRODUCT SPECIFICATION

MOLEX P/N	DESCRIPTION	HEADER PIN OUT	HEADER BLADE PLATING	CONNECTOR P/N (MOLEX)
203161001 203161101	MPDB_MOD_ASSY 8CKT KEY-B	8-WAY (6X1.5 & 2X6.3)	1.5:TIN / 6.3:AG	160078-3024
203161002 203161102	MPDB_MOD_ASSY 8CKT KEY-A	8-WAY (6X1.5 & 2X6.3)	1.5:TIN / 6.3:TIN	160078-3022
203161003 203161103	MPDB_MOD_ASSY 10CKT KEY-C	8-WAY (6X1.5 & 2X6.3)	1.5:TIN / 6.3:TIN	160076-3026
203161021 203161121	MPDB_ASSY 8CKT KEY-A	8-WAY (6X1.5 & 2X6.3)	1.5:TIN / 6.3:TIN	160078-3006
203161022 203161122	MPDB_MASSY 10CKT KEY-B	8-WAY (6X1.5 & 2X6.3)	1.5:TIN / 6.3:TIN	160076-3007

2.2 EXTERNAL DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS



MATERIAL:

DESCRIPTION	Material Description	PLATING / (COLOR)
SHROUD HEADER (8W, 9W, 10W)	PBT GF30%, LR	(BLK)
150 BLADE (LONG / SHORT)	C26000 H03	TIN
280 BLADE (LONG / SHORT)	C19400 H08	TIN
630 BLADE	C19400 H08	TIN / SILVER
BACK COVER	PBT GF30%, LR	(BLK)
PCB	FR-4 / Tg=170C	
RELAY	SEE SCHEMATIC	
FUSE	SEE SCHEMATIC	
RESISTER	SEE SCHEMATIC	

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PRODUCT SPECIFICATION

MARKING: PRODUCT TRACEABILITY



TRACEABILITY LASER MARKING:

* 2D DATA MATRIX CODE (2D DMC)

- MARKING AND READING STANDARD: DATA MATRIX (ECC200)
- 14MM X 14MM SIZE
- INFORMATION TO BE ENCODED:
 PPPP = LAST FOUR DIGITS OF MOLEX PART NUMBER
 YY=YEAR
 DDD=DAY OF THE YEAR
 SSSS=INCREMENTAL SERIAL NUMBER

* HUMAN READABLE CODE (HRC)

- 10 DIGITS MOLEX PART NUMBER
- 5 DIGITS JULIAN MANUFACTURING DATE (DDYY)
- 4 DIGITS INCREMENTAL SERIAL NUMBER

* BLANKED BOX AREA

- OPTIONAL CONSTRUCTION PER CUSTOMER'S TRACEABILITY REQUIREMENT

PENDING APPROVAL

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DOCUMENT NUMBER: PS-200316-1000		CREATED / REVISED BY: E.H. CHEONG	CHECKED BY: E.H. CHEONG
		APPROVED BY: RON BAUMAN	

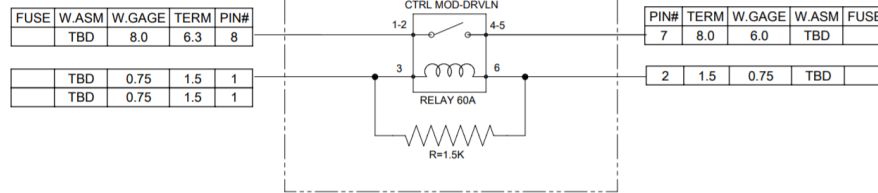


PRODUCT SPECIFICATION

2.3 SCHEMATIC

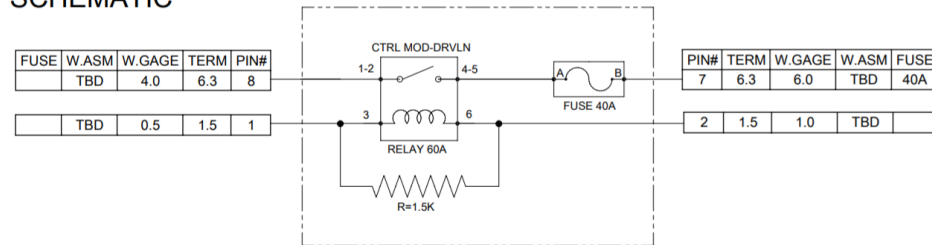
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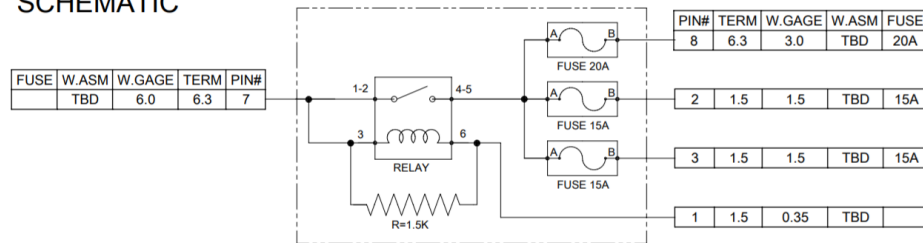
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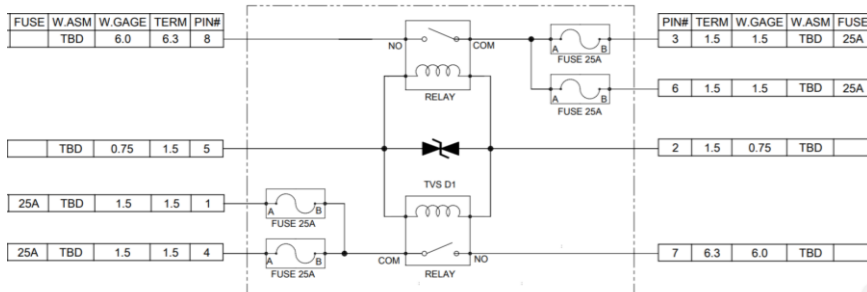


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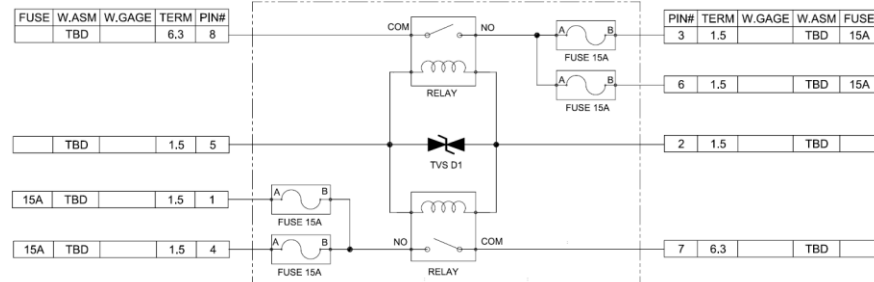


200316-1021
200316-1121



200316-1022
200316-1122

SCHEMATIC



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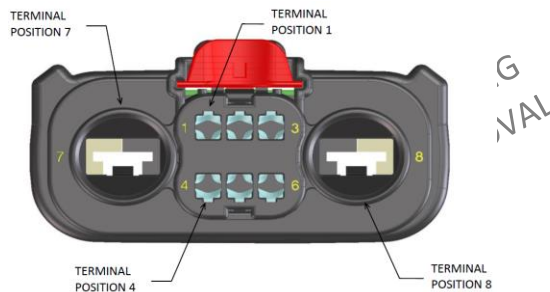
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PRODUCT SPECIFICATION

2.4 MATING CONNECTOR & TERMINALS:

Micro-PDB P/N	Molex Connector P/N	Connector Description	Terminal P/N (Supplier)	Terminal Description
2003161001 2003161101	160078-3024	MX150 1.5/6.3 HYBRID 8 WAY SEALED RECEPTACLE CONNECTOR KEY_B (W/CPA, BLK) BLOCKED (3,4,5,6)	Delphi: TBD	FCI / Delphi APEX 6.3 Female Sealed, TIN/AG Plated, Greased 761G, 8.0 mm ²
			Molex: 33012-2002	Molex MX-150 Female MAT Seal, TIN Plated, Payoff-Right (D) 0.75-1.0 mm ² (20-18 AWG)
2003161002 2003161102	160078-3022	MX150 1.5/6.3 HYBRID 8 WAY SEALED RECEPTACLE CONNECTOR KEY_A (W/CPA, BLK) BLOCKED (3,4,5,6)	Delphi: 33140138	FCI / Delphi APEX 6.3 Female Sealed, TIN/AG Plated, Greased 761G, 4.0-6.0 mm ² (12-10 AWG)
			Molex: 33012-2002	Molex MX-150 Female MAT Seal, TIN Plated, Payoff-Right (D) 0.75-1.0 mm ² (20-18 AWG)
2003161003 2003161103	160078-3026	MX150 1.5/6.3 HYBRID 8 WAY SEALED RECEPTACLE CONNECTOR KEY_C (W/CPA, BLK) BLOCKED (4,5,6)	Delphi: 33140138	FCI / Delphi APEX 6.3 Female Sealed, TIN/AG Plated, Greased 761G, 4.0-6.0 mm ² (12-10 AWG)
			Molex: 33012-2002 33012-2002	Molex MX-150 Female MAT Seal, TIN Plated, Payoff-Right (D) 0.75-1.0 mm ² (20-18 AWG) 1.50-2.0 mm ² (16-14 AWG)
2003161021 2003161121	160078-3006	MX150 1.5/6.3 HYBRID 8 WAY SEALED RECEPTACLE CONNECTOR KEY_A (W/CPA, BLK) BLOCKED (NONE)	Delphi: 33140138	FCI / Delphi APEX 6.3 Female Sealed, TIN/AG Plated, Greased 761G, 4.0-6.0 mm ² (12-10 AWG)
			Molex: 33012-2002 33012-2002	Molex MX-150 Female MAT Seal, TIN Plated, Payoff-Right (D) 0.75-1.0 mm ² (20-18 AWG) 1.50-2.0 mm ² (16-14 AWG)
2003161022 2003161122	160078-3007	MX150 1.5/6.3 HYBRID 8 WAY SEALED RECEPTACLE CONNECTOR KEY_B (W/CPA, BLK) BLOCKED (NONE)	Delphi: 33140138	FCI / Delphi APEX 6.3 Female Sealed, TIN/AG Plated, Greased 761G, 4.0-6.0 mm ² (12-10 AWG)
			Molex: 33012-2002 33012-2002	Molex MX-150 Female MAT Seal, TIN Plated, Payoff-Right (D) 0.75-1.0 mm ² (20-18 AWG) 1.50-2.0 mm ² (16-14 AWG)



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PRODUCT SPECIFICATION

2.5 SPECIFICATION:

Micro-PDB		2003161001 2003161101	2003161002 2003161102	2003161003 2003161103
General	Application:	Cooling Fan Module	DRVLN Module	UREA Module
	Weight:	63.0 (g)	66.6 (g)	58.0 (g)
	Sealing Performance:	IP Code: IP6K7		
	Operating Temperature:	-40°C to +110°C		
Mechanical	Header design:	8W Hybrid Sealed Key-B	8W Hybrid Sealed Key-A	8W Hybrid Sealed Key-C
	Blade Material / Plating:	2 X 6.3 Blade: C19400 / AG	2 X 6.3 Blade: C19400 / TIN	2 X 6.3 Blade: C19400 / TIN
		6 X 1.5 Blade: C26000 / TIN	6 X 1.5 Blade: C26000 / TIN	6 X 1.5 Blade: C26000 / TIN
	Clip Slot for Mounting:	11.0 mm Per EWCAP-005-11		
Mating Connector:	Molex MX-150 Sealed P/N: 160078-3024 (Blocked: 3,4,5,6)	Molex MX-150 Sealed P/N: 160078-3022 (Blocked: 3,4,5,6)	Molex MX-150 Sealed P/N: 160078-3026 (Blocked: 4,5,6)	
Electrical	Operating Voltage	6 to 14.5V DC		
	Operating Voltage (Coil)	7.3-16V DC (@25C)*		
	Steady State Cur. (Nom.)	#7-48A / 13.5 V	#8-25A / 13.5 V	#8-7.5A, #2-6A, #3-7.5A / 13.5 V
	Steady State Cur. (Max.)	#7-51A / 14.5 V	#8-30A / 14.5 V	21A / 14.5 V
	In-Rush Current:	122.4A / 0.001 Sec	60A / 0.025 Sec	
	No of Relays X Rating	1 X 60A	1 X 60A	1 X 30A
	Circuit Protection	No	LPJ-Fuse: #7-40A	Micro-2: #8-20A, #2-15A, #1-15A

Micro-PDB		2003161021 2003161121	2003161022 2003161122	
General	Application:	Glow Plug Module (12V)	Glow Plug Module (24V)	
	Weight:	XX.X (g)	XX.X (g)	
	Sealing Performance:	IP Code: IP6K7		
	Operating Temperature:	-40°C to +110°C		
Mechanical	Header design:	8W Hybrid Sealed Key-A	8W Hybrid Sealed Key-B	
	Blade Material / Plating:	2 X 6.3 Blade: C19400 / TIN	2 X 6.3 Blade: C19400 / TIN	
		6 X 1.5 Blade: C26000 / TIN	6 X 1.5 Blade: C26000 / TIN	
	Clip Slot for Mounting:	11.0 mm Per EWCAP-005-11		
Mating Connector:	Molex MX-150 Sealed P/N: 160078-3006 (Blocked: None)	Molex MX-150 Sealed P/N: 160078-3007 (Blocked: None)		
Electrical	Operating Voltage	6.5- 16V DC	13.3-32V DC	
	Operating Voltage (Coil)	6-16V DC (@25C)*	7.2-16V DC (@25C)	
	Steady State Cur. (Nom.)	#1, #3, #4, #6-28A / 13.5 V	#1, #3, #4, #6-15A/13.5V	
	Steady State Cur. (Max.)			
	In-Rush Current:	80A / 5 sec @15C	48A / 5sec @15C	
	No of Relays X Rating	2 X 40A (One control line)	2 X 15A-24V (One control line)	
Circuit Protection	Micro-2: 4 X 25A	Micro-2: 4 X 15A		

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PRODUCT SPECIFICATION

2.6 SAFETY AGENCY APPROVALS

UL File Number	Not Applicable
CSA File Number	Not Applicable
TUV License number	Not Applicable

2.7 APPLICABLE DOCUMENTS AND SPECIFICATIONS

Description	Document Number
LOAD DATA /	EACH APPLICATION LOAD DATA
DV & PV TEST SPECIFICATION	ESGU5T-14A067-AB
ELECTROMAGNETIC COMPATIBILITY SPECIFICATION FOR ELECTRICAL/ELECTRONIC COMPONENTS AND SUBSYSTEMS	FMC-1278 (EMC-CS-2009.1)
COSMETIC SPECIFICATION	PS-45499-002 (CLASS B)
USCAR STANDARD BLADE MATERIAL & PLATING SELECTION	EWCAP-001
TRACEABILITY LABEL	MOLEX TRACEABILITY SPEC.
GENERAL STANDARD OF PCB DESIGN	IPC-2221
ADHESIVE MATERIAL SPECIFICATION	MOLEX P/N 31415-0300
IDC DESIGN SPECIFICATION	8W: 999-S-008-2-Z-1 9W: 999-S-009-2-Z-1 10W: 999-S-010-2-Z-1
X-MAS TREE CLIP: HELLERMANN TYTON	COMPATIBLE USCAR 11.0MM: Reference: Helleermann Tyton P/N: 151-01199
USCAR DESIGN STANDARD FOR CLIP SLOT	EWCAP-005-11

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PRODUCT SPECIFICATION

3.0 PERFORMANCE

3.1 ELECTRICAL PERFORMANCE

No.	Test Name	Test Spec. / Procedures	Performance	Requirements
1	EMC/Electrical Environment	FMC-1278 (EMC-CS-2009.1)	Met	Perform test for "Other Device-R" component category: -CE 410 -CI 270 ABC
2	100% Continuity Test	ESGU5T-14A067-AB Test # 1.	Met	Continuity through each circuit.
3	Thermal Mapping Test	ESGU5T-14A067-AB Test # 2.	Met	Temp rise > 55°C ROA (Rise Over Ambient) and/or not exceed the Heat Deflection Temp. HDT @ 460 KPa.
4	Power Dissipation Test.	ESGU5T-14A067-AB Test # 3.	Met	1) No visible distortion assemblies or parts. No discoloration / overheating of PCB traces, terminals, components. 2) Temp rise > 55°C ROA (Rise Over Ambient) and/or not exceed the Heat Deflection Temp. HDT @ 460 KPa. 3) Voltage drop shall not exceed (1.0 mV/A) * (Number of Crimps) + (2.0 mV/A) * (Number of Interfaces) + (Number of Solder Joints x 0.5 mV/A).
5	135% Fuse/Circuit Breaker Load Test	ESGU5T-14A067-AB Test # 5.	Met	1) Open circuit within specified circuit protection guideline. 2) No plastic flow or terminal fusing.
6	Dielectric Test	ESGU5T-14A067-AB Test # 6.	Met	Leakage Current < 1mA.
7	Insulation Resistance Test	ESGU5T-14A067-AB Test # 7.	Met	Insulation Resistance > 10 MΩ.
8	Key Life Test	ESGU5T-14A067-AB Test # 8.	Met	1) No breakage, degradation affecting performance. Label/Graphics must not crack, flake or bubble. 2) Temp rise > 55°C ROA (Rise Over Ambient) and/or not exceed the Heat Deflection Temp. HDT @ 460 KPa. 3) Voltage drop shall not exceed (1.0mV/A) * (number of crimps + (2.0mV/A) * (number of interfaces).

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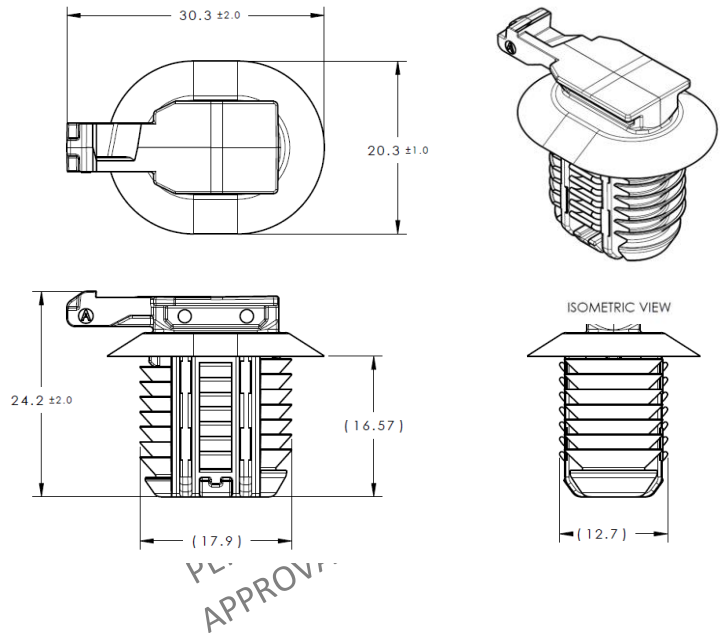
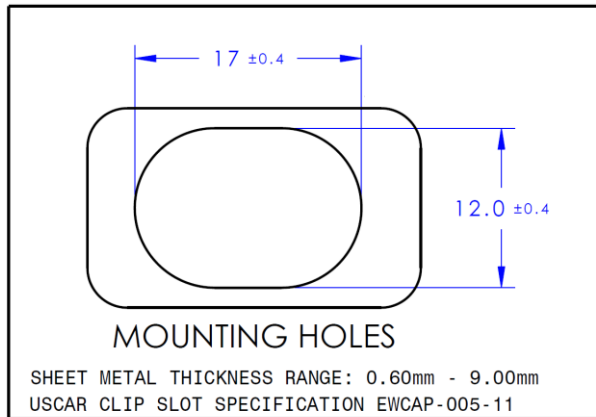
PRODUCT SPECIFICATION

3.2 MECHANICAL PERFORMANCE

No.	Test Name	Test Spec. / Procedures	Performance	Requirements
1	Connector Mating and Un-Mating Force	Mating Force: SAE/USCAR-25, GMW3172 Un-Mating Force: ESGU5T-14A067-AB Test # 33.	Met	Mating Force: $\leq 75N$ Un-Mating Force: $\geq 110N$
2	Terminal Retention Force	ESGU5T-14A067-AB Test # 22.	Met	Terminal Retention Force: 2.8 & 6.3 Blade: Min. 112N 1.5 Blade: Min. 75N
3	Component Cover Retention Force	ESGU5T-14A067-AB Test # 28.	Met	Retention Force: $\geq 220N$
4	Mechanical Vibration and Mechanical Shock	ESGU5T-14A067-AB Test # 18.	Met	Pass 100% Continuity Test and no audible RBS
5	Drop Test	ESGU5T-14A067-AB Test # 30. Reference CETP 00.00-E-412	Met	Pass 100% Continuity Test and no audible RBS
6	Insertion / Extraction Force: Clip into Clip Slot	USCAR-2 Rev 5: Sec. 5.4.5	Met	Engage Force: $< 60N$. Disengage Force: $> 110N$.
7*	Mounting Force to Bracket	ESGU5T-14A067-AB Test #32	Met	Engage Force: $\leq 90N$.

Notes: (*)

7: Sheet Metal design for X-Mas Clip Mounting:



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PRODUCT SPECIFICATION

3.3 ENVIROMENTAL PERFORMANCE

No.	Test Name	Performance	Test Spec. / Procedures	Requirements
1	Thermal Shock Resistance Test	Met	ESGU5T-14A067-AB Test # 9. Reference: CETP 00.00-E-412	1) Voltage drop shall not exceed (1.0mV/A) * (number of crimps + (2.0mV/A) * (number of interfaces). 2) No visible cracks, distortions. 3) Remove / Reinstall connector 20 times. No degradation performance.
2	Low Temperature Exposure Test	Met	ESGU5T-14A067-AB Test # 10. Reference: CETP 00.00-E-412	1) No visible cracks, distortions. 2) Remove / Reinstall connector 20 times. No degradation performance.
3	High Temperature Exposure Test	Met	ESGU5T-14A067-AB Test #10. Reference: CETP 00.00-E-412	1) No visible cracks, distortions. 2) Remove / Reinstall connector 20 times. No degradation performance.
4	Humidity - Temperature Cycle Test	Met	ESGU5T-14A067-AB Test # 12. Reference: CETP 00.00-E-412	1) Voltage drop shall not exceed (1.0mV/A) * (number of crimps + (2.0mV/A) * (number of interfaces). 2) No visible cracks or distortions. 3) Max. Leak current < 1mA.
5	Dust Test	Met	ESGU5T-14A067-AB Test # 13. Reference: CETP 00.00-E-412	1) Voltage drop shall not exceed (1.0mV/A) * (number of crimps) + (2.0mV/A) * (number of interfaces).
6	Salt Spray Test	Met	ESGU5T-14A067-AB Test # 14 Reference : CETP 00.00-E-412	1) Max. Leak current < 1mA. 2) Voltage drop shall not exceed (1.0mV/A) * (number of crimps) + (2.0mV/A) * (number of interfaces).
7	Heavy Splash/Shower Test	Met	ESGU5T-14A067-AB Test # 15. Reference: CETP 00.00-E-412, 5.9.3	Max. Leak current < 1mA.
9	Water Dump Test	Met	ESGU5T-14A067-AB Test # 17. Reference: CETP 00.00-E-412	No evidence of water intrusion into areas of PCB in the EDB.
10	Chemical Resistance Test	Met	ESGU5T-14A067-AB Test # 31	1) Max. Leak current < 1mA. 2) No degradation in the performance 3) No crack, flake, bubble or deteriorate in the plastic, labels...

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PRODUCT SPECIFICATION

4.0 PACKAGING

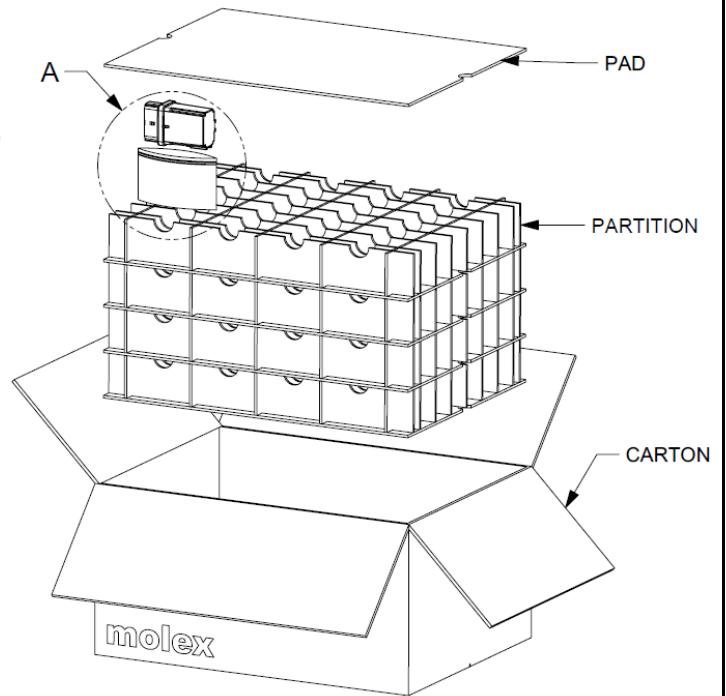
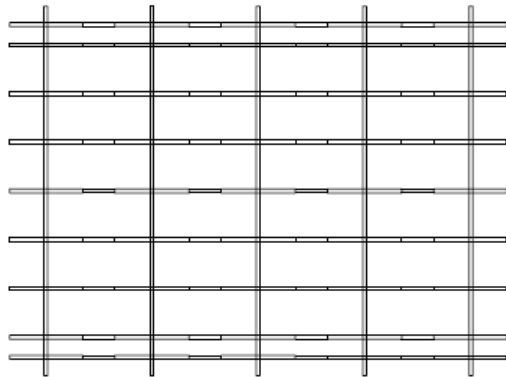
Parts shall be packaged to protect against damage during handling, transit and storage.

PART #	CARTON #	PARTITION #	PAD #	BAG #	QTY/ BAG	BAGS/ PARTITION	QTY/ PARTITION	PARTITIONS/ CARTON	PADS/ CARTON	QTY/ CARTON	CARTONS/ PALLET	SPQ	MOQ
200316100X (X=1-8)	477991201	2003169300	2003169301	2003169302	1	24	24	4	5	96	32	96	3072

Molex Drawing No: PK-2003168103

Max. Q'ty: 96 Pcs / Carton Box
Total 4 Layers / Carton (with 24 Cells per Layer)

PARTITION: 24 CELLS



5.0 GAGES AND FIXTURES

All applicable gages and fixtures are referenced in the appropriate control plans.

6.0 OTHER INFORMATION

To ensure compliance with our product validation, it is imperative that our product meet the drawing specifications. Any non-conformance with the key functional dimensions or mating interface will create performance failures.

PENDING APPROVAL

REVISION: B	ECR/ECN INFORMATION: ER No: 626413 DATE: 2019 / 10 / 28	TITLE: PS: MICRO-PDB_MODULE ASSEMBLY	SHEET No. 12 of 12
DOCUMENT NUMBER: PS-200316-1000	CREATED / REVISED BY: E.H. CHEONG	CHECKED BY: E.H. CHEONG	APPROVED BY: RON BAUMAN